

## N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

## **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

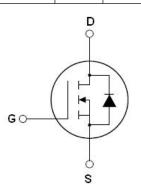
#### **Features**

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V <sub>DS min@Tjmax</sub>	650	V
R <sub>DS(ON)TYP</sub>	70	mΩ
ID	41	Α
Qg	53	nC



Schematic diagram

♦ Intrinsic fast-recovery body diode

#### **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE60NF080D	TO-263	NCE60NF080D



TO-263

#### Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	V <sub>DS</sub>	600	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	V <sub>G</sub> s	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	41	Α
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	28.7	Α
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	123	Α
Maximum Power Dissipation(Tc=25°C)	P <sub>D</sub>	351	W
Derate above 25°C		2.34	w/°C
Single pulse avalanche energy (Note 2)	Eas	400	mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AS</sub>	10	Α
Repetitive Avalanche energy ,t <sub>AR</sub> limited by T <sub>jmax</sub> (Note 1)	Ear	0.7	mJ
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V <sub>DS</sub> ≤480 V,I <sub>SD</sub> <i<sub>D</i<sub>	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55+175	°C



<sup>\*</sup> limited by maximum junction temperature

**Table 2. Thermal Characteristic** 

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	0.427	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =500uA 600				V
Zero Gate Voltage Drain Current(Tc=25°C)	I <sub>DSS</sub>	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V			300	μΑ
Gate-Body Leakage Current	Igss	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	3	4	5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A		70	80	mΩ
Dynamic Characteristics						
Input Capacitance	C <sub>lss</sub>	\/ F0\/\/ 0\/		2920		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V, F=1.0MHz		123		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0IVIH2		5.4		pF
Total Gate Charge	Qg			53		nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =480V,I <sub>D</sub> =20A,		17		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V		13		nC
Gate plateau voltage	Vgp			6.8		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		1.0		Ω
Switching times	·					
Turn-on Delay Time	t <sub>d(on)</sub>			31		nS
Turn-on Rise Time	tr	$V_{DD}$ =380 $V$ , $I_{D}$ =20 $A$ ,		13		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G=1.7\Omega, V_{GS}=10V$		89		nS
Turn-Off Fall Time	t <sub>f</sub>			8		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	Isp	T -25°C			41	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			123	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =41A,V <sub>GS</sub> =0V		1.0	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T:-25°C L -20A		120		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I <sub>F</sub> =20A,		0.48		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>	di/dt=100A/μs		8		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25  $^{\circ}\text{C}$  ,VDD=50V,VG=10V, RG=25 $\Omega$ 



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

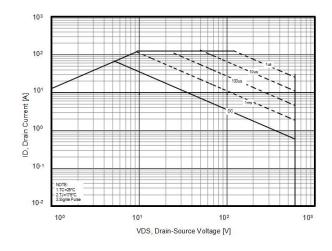


Figure 2. Capacitance

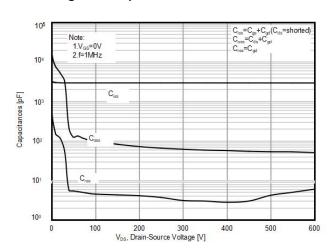


Figure 3. Source-Drain Diode Forward Voltage

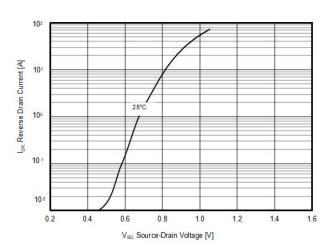


Figure 4. Output characteristics

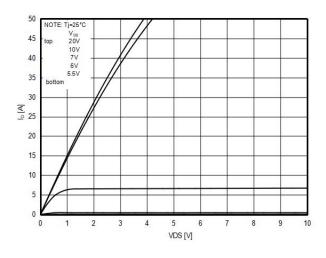


Figure 5. RDS(ON) vs Junction Temperature

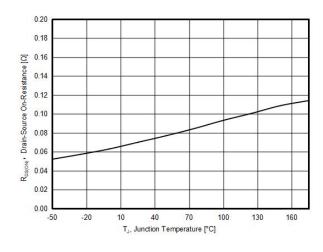


Figure 6. BV<sub>DSS</sub> vs Junction Temperature

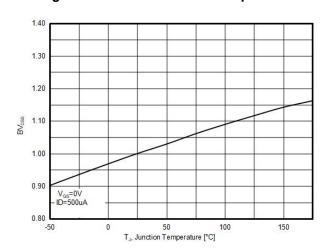




Figure 7. Maximum I<sub>D</sub> vs Junction Temperature

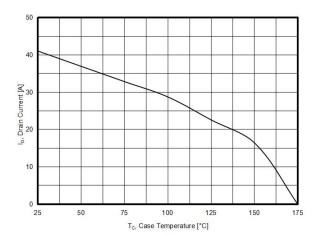


Figure8. Gate charge waveforms

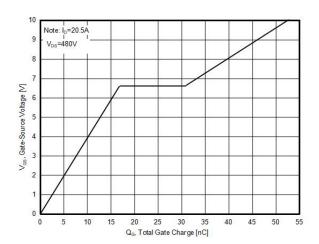


Figure 9. Static drain-source on resistance

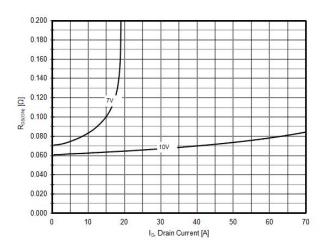
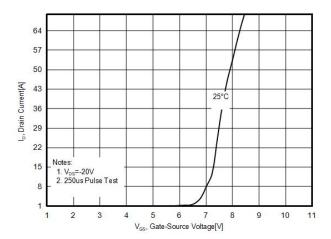


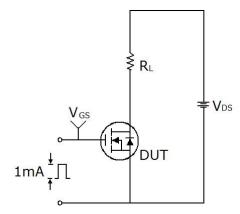
Figure 10. Transfer characteristics

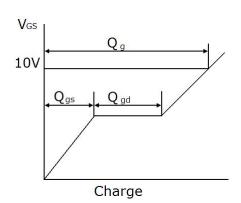




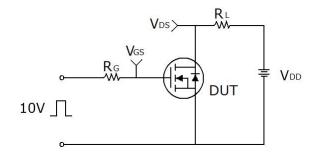
## **Test circuit**

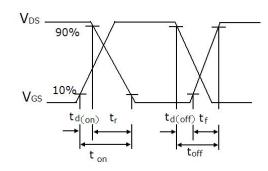
### 1) Gate charge test circuit & Waveform



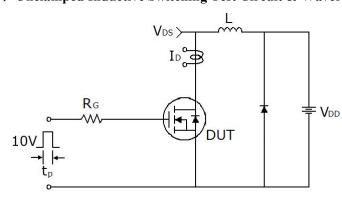


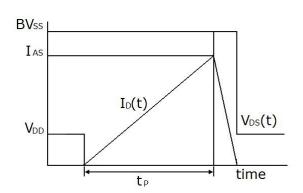
## 2) Switch Time Test Circuit:





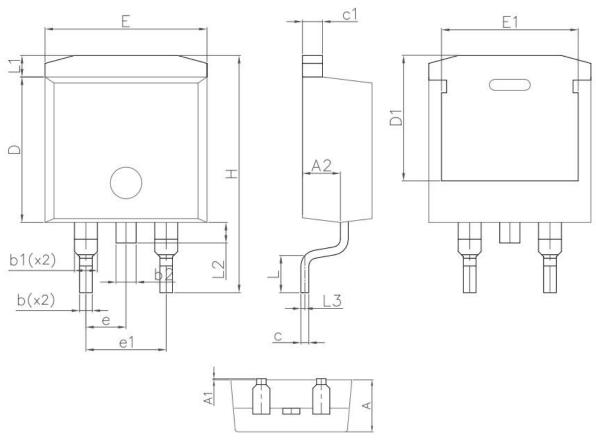
## 3) Unclamped Inductive Switching Test Circuit & Waveforms







# **TO-263-E** Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
А	4.20	4.60	0.165	0.181		
A1	0.00	0.25	0.00	0.010		
A2	2.20	2.60	0.087	0.102		
b	0.70	0.90	0.028	0.035		
b1	1.20	1.75	0.047	0.069		
b2	1.17	1.37	0.046	0.054		
С	0.40	0.60	0.016	0.024		
c1	1.15	1.40	0.045	0.055		
D	9.10	9.30	0.358	0.366		
D1	7.63	8.23	0.300	0.324		
E	10.05	10.45	0.396	0.411		
E1	8.35	8.95	0.329	0.352		
е	2.54	IBSC	0.100BSC			
e1	5.08BSC		0.200BSC			
Н	14.61	15.88	0.575	0.625		
L	1.78	2.79	0.070	0.110		
L1	1.36	1.36REF		0.054REF		
L2	1.30	REF	0.051	REF		



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